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PCB stack-up for fabrication

Layer	Name	Assignment
1	Top	Components, routing
2	GND	Ground
3	SIG	Signal, Power
4	Bottom	Routing

Revision History

[illegible]

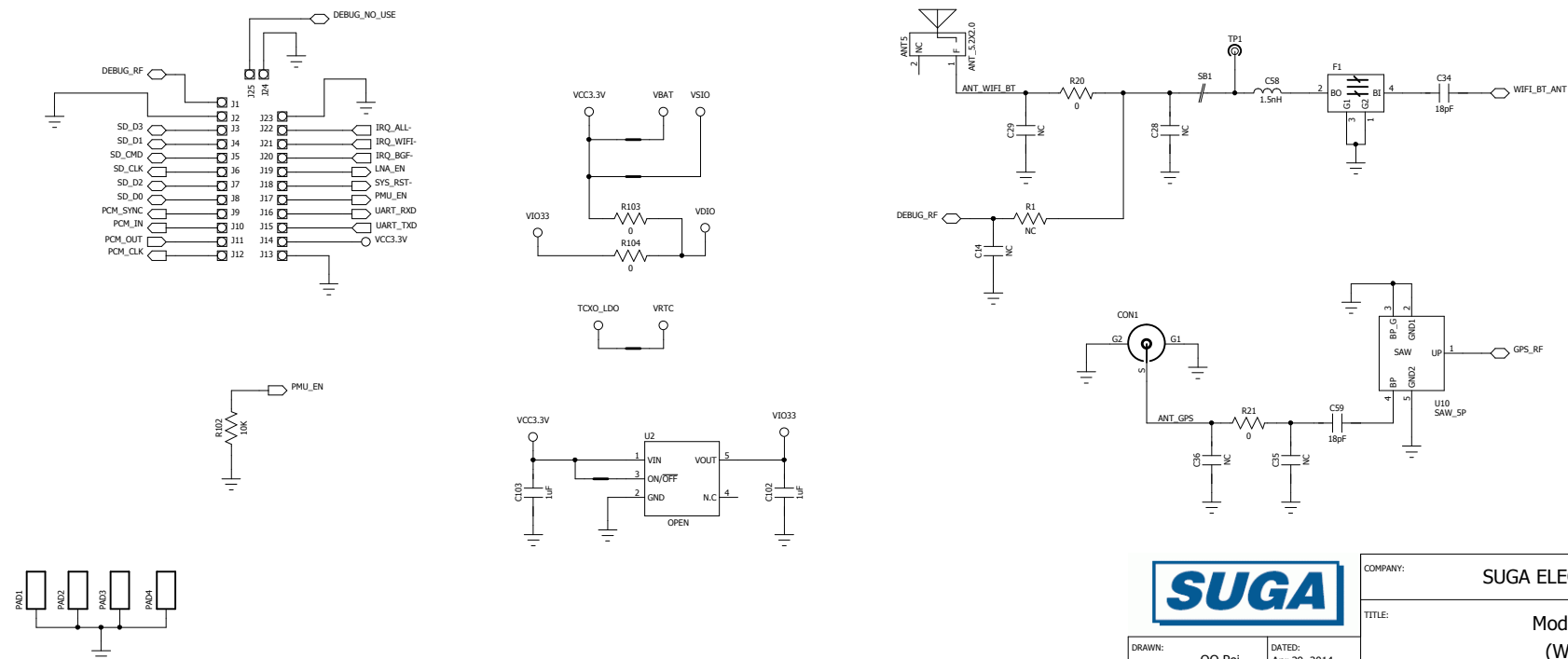
REVISION RECORD			
LTR	ECO NO:	APPROVED:	DATE:

PCB requirements

Dimension: TBC
Thickness: 1.0mm
Number of layers: 4
Copper thickness: 0.5oz top & bottom; 1oz all internal layers.
Material: FR4, Low CTE, Tg>=140 degree
Surface treatment: immersion gold plated (ENIG).
Minimum wire width and spacing: 5mil (0.127mm)
Minimum via hole diameter: 10mil (0.254mm)

Unless otherwise specified:

Resistors are SMD(0402) are +/-5%, 1/16W
Resistors specified as SMD(0603) are +/-5%, 1/10W
Resistors specified as SMD(0805) are +/-5%, 1/8W
Ceramic capacitors >= 10uF are SMD(0805)
Ceramic capacitors >= 0.22uF, <10uF, are SMD(0603)
Ceramic capacitors <= 0.1uF are SMD(0402)
Ceramic and Electrolytic capacitors are 6.3V or higher
Ferrite beads are SMD(0402).



<CONFIDENTIAL>



DRAWN: QQ Pei		DATED: Apr 29, 2014		(Wifi+BT+GPS)			
CHECKED: TONY TSANG		DATED: Apr 29, 2014					
QUALITY CONTROL:		DATED:		CODE:	SIZE: A2	DRAWING NO:	REV: V1.0
RELEASED:		DATED:					
SCALE:				SHEET: 1 OF 2			

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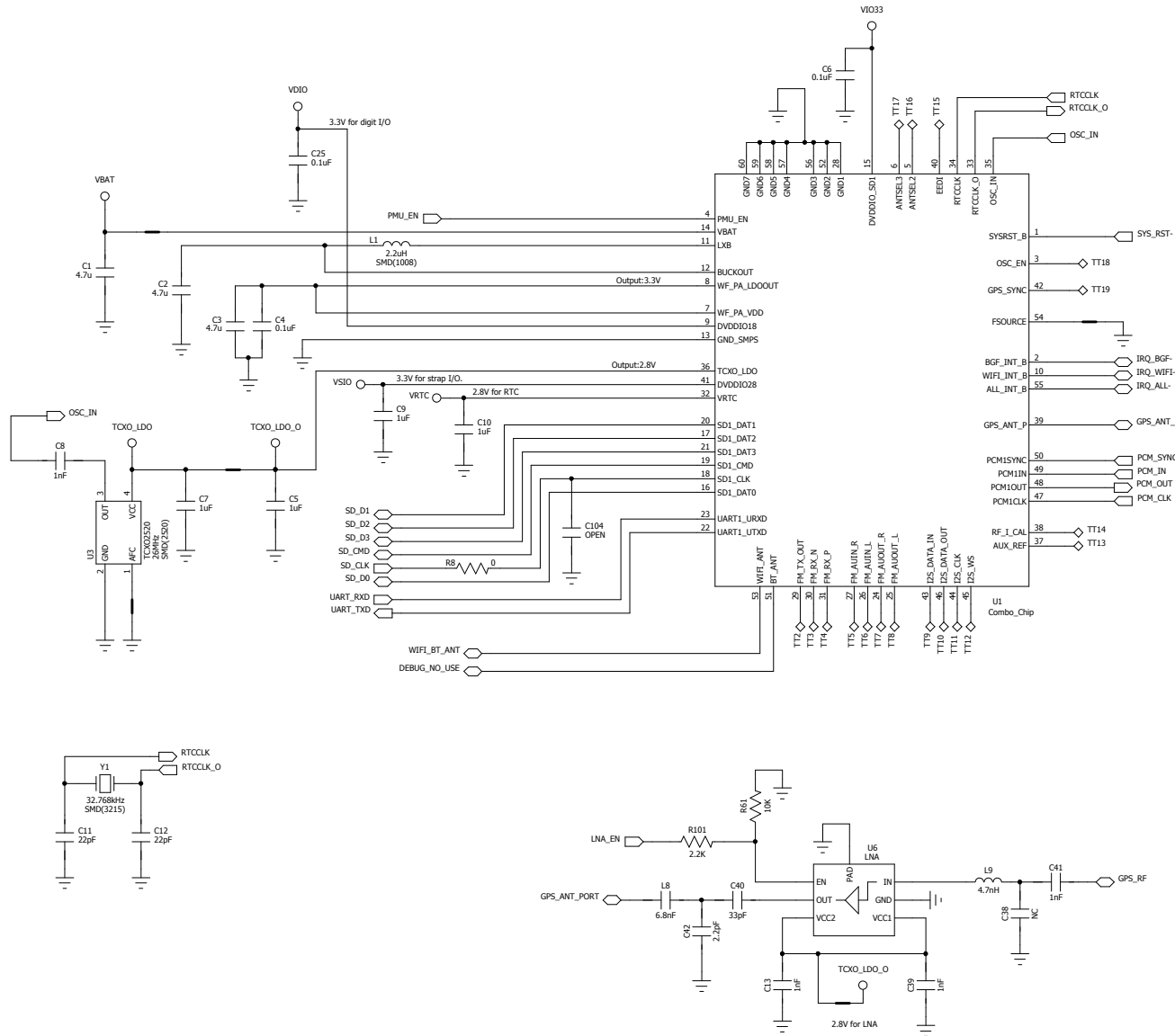
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*** MT6620_SIP ***

REVISION RECORD			
LTR	ECO NO:	APPROVED:	DATE:



COMPANY: SUGA ELECTRONICS LTD.			
TITLE: Model SWBGFSA-0 (Wifi+BT+GPS)			
CODE:	SIZE: A2	DRAWING NO:	REV: V1.0
RELEASED:	DATED:	SHEET: 2 OF 2	

DRAWN: QQ Pei	DATED: Apr 29, 2014
CHECKED: TONY TSANG	DATED: Apr 29, 2014
QUALITY CONTROL:	DATED:
RELEASED:	DATED: